

# MUR550APF, MURD550PF, MUR550PF

Preferred Device

## SWITCHMODE™ Power Rectifier

These state-of-the-art devices are designed for power factor correction in discontinuous and critical conduction mode.

### Features and Benefits

- 520 V Rating Meets 80% Derating Requirements of Major OEMs
- Low Forward Voltage Drop
- Low Leakage
- Ultrafast 95 Nanosecond Recovery Time
- Reduces Forward Conduction Loss
- Pb-Free Package is Available

### Applications

- DCM PFC Designs
- Switching Power Supplies
- Power Inverters

### Mechanical Characteristics

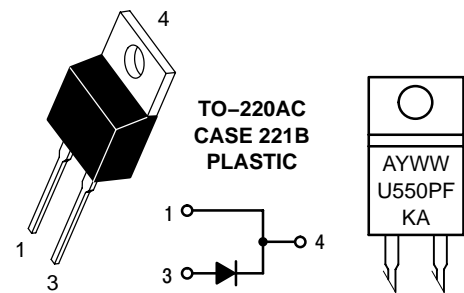
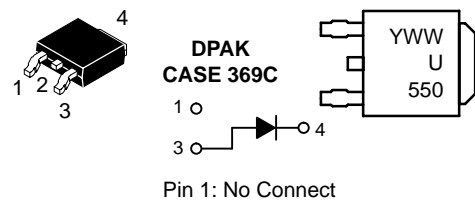
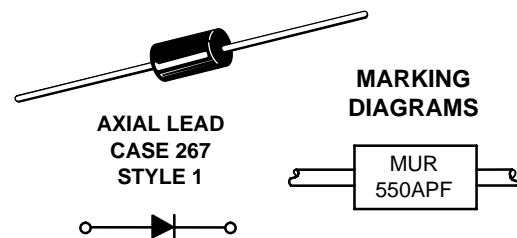
- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: MUR550APF: 1.1 Gram (Approximately)  
MURD550PF: 0.4 Gram (Approximately)  
MUR550PF: 1.9 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 220°C Max. for 10 Seconds



**ON Semiconductor®**

<http://onsemi.com>

## ULTRAFAST RECTIFIER 5.0 A, 520 V



MUR550APF, = Device Code  
U550PF

A = Assembly Location  
Y = Year  
WW = Work Week  
KA = Diode Polarity

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

[www.DataSheet4U.com](http://www.DataSheet4U.com)

# MUR550APF, MURD550PF, MUR550PF

## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	520	V
Average Rectified Forward Current (Rated $V_R$ ) $T_C = 65^\circ\text{C}$ MUR550APF (Rated $V_R$ ) $T_C = 160^\circ\text{C}$ MURD550PF, MUR550PF	$I_{F(AV)}$	5.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, 60 Hz) MUR550APF MURD550PF MUR550PF	$I_{FSM}$	85 75 100	A
Operating Junction Temperature Range	$T_J$	-65 to +175	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-65 to +175	$^\circ\text{C}$
ESD Ratings: Machine Model = C Human Body Model = 3B	ESD	> 400 >8000	V

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

## THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Resistance – Junction-to-Case (Note 1) MURD550PF, MUR550PF	$R_{\theta JC}$	2.8	$^\circ\text{C/W}$
Thermal Resistance – Junction-to-Ambient MUR550APF MURD550PF (Note 3)	$R_{\theta JA}$	Note 2 62	$^\circ\text{C/W}$

## ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage Drop (Note 4) ( $I_F = 5.0\text{ A}$ , $T_J = 25^\circ\text{C}$ ) ( $I_F = 5.0\text{ A}$ , $T_J = 150^\circ\text{C}$ )	$V_F$	1.15 0.98	V
Maximum Instantaneous Reverse Current (Note 4) ( $V_R = 520\text{ V}$ , $T_J = 25^\circ\text{C}$ ) ( $V_R = 520\text{ V}$ , $T_J = 150^\circ\text{C}$ )	$I_R$	5.0 400	$\mu\text{A}$
Maximum Reverse Recovery Time ( $I_F = 1.0\text{ A}$ , $di/dt = 50\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$ , $T_J = 25^\circ\text{C}$ )	$t_{rr}$	95	ns

1. Rating applies when surface mounted on the minimum pad sizes recommended.
2. See Note 2, Ambient Mounting Data.
3. 1 inch square pad size on FR4 board.
4. Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

# MUR550APF, MURD550PF, MUR550PF

## NOTE 2 — AMBIENT MOUNTING DATA

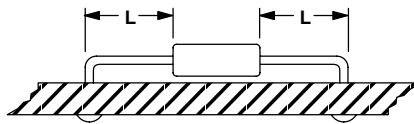
Data shown for thermal resistance junction-to-ambient ( $R_{\theta JA}$ ) for the mountings shown is to be used as typical guideline values for preliminary engineering or in case the tie point temperature cannot be measured.

### TYPICAL VALUES FOR $R_{\theta JA}$ IN STILL AIR

Mounting Method	$R_{\theta JA}$	Lead Length, L (IN)				Units
		1/8	1/4	1/2	3/4	
1		50	51	53	55	$^{\circ}\text{C}/\text{W}$
2		58	59	61	63	$^{\circ}\text{C}/\text{W}$
3		28				$^{\circ}\text{C}/\text{W}$

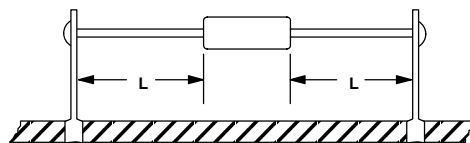
#### MOUNTING METHOD 1

P.C. Board Where Available Copper Surface area is small.



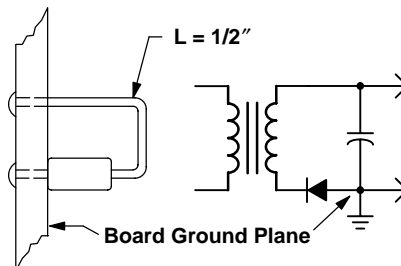
#### MOUNTING METHOD 2

Vector Push-In Terminals T-28



#### MOUNTING METHOD 3

P.C. Board with 1-1/2" x 1-1/2" Copper Surface



# MUR550APF, MURD550PF, MUR550PF

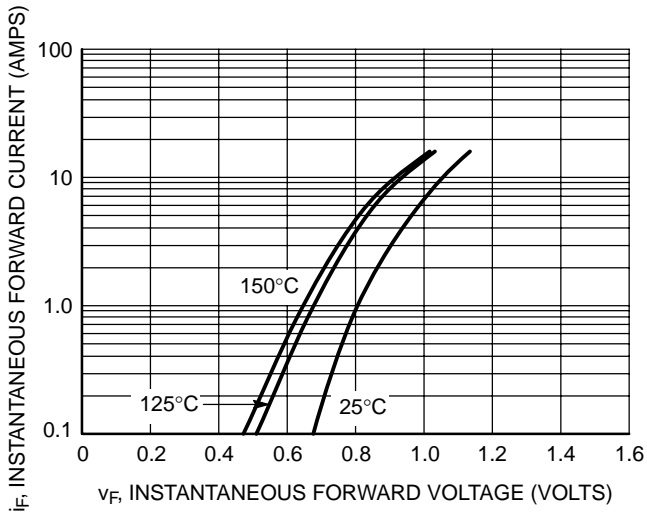


Figure 1. Typical Forward Voltage

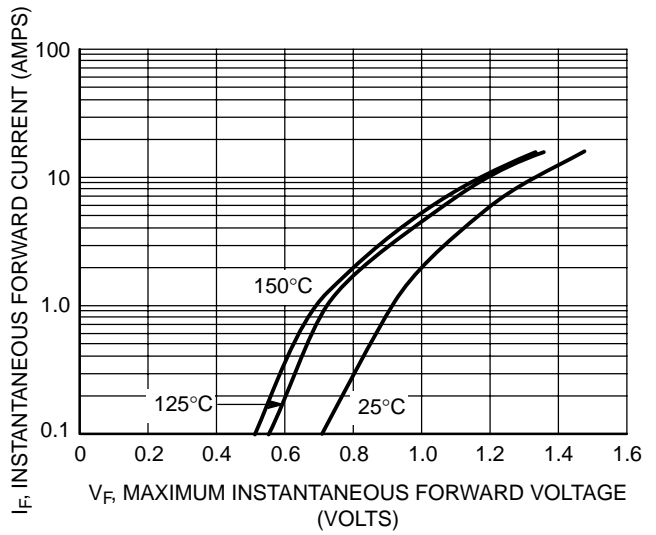


Figure 2. Maximum Forward Voltage

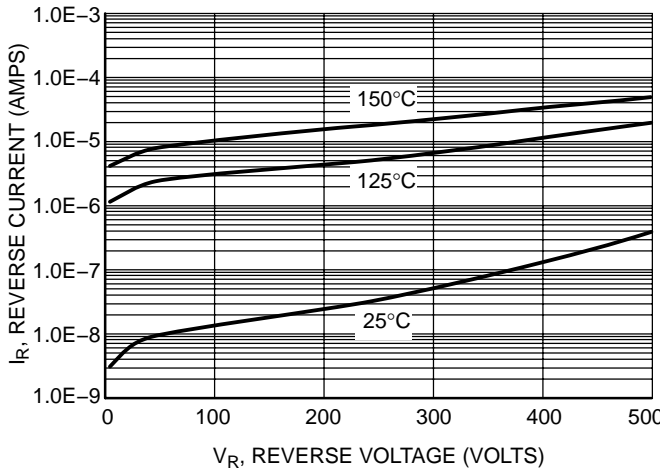


Figure 3. Typical Reverse Current

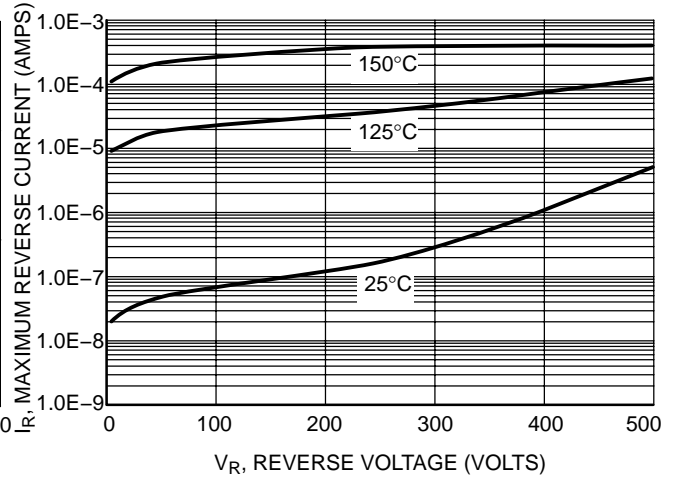


Figure 4. Maximum Reverse Current

# MUR550APF, MURD550PF, MUR550PF

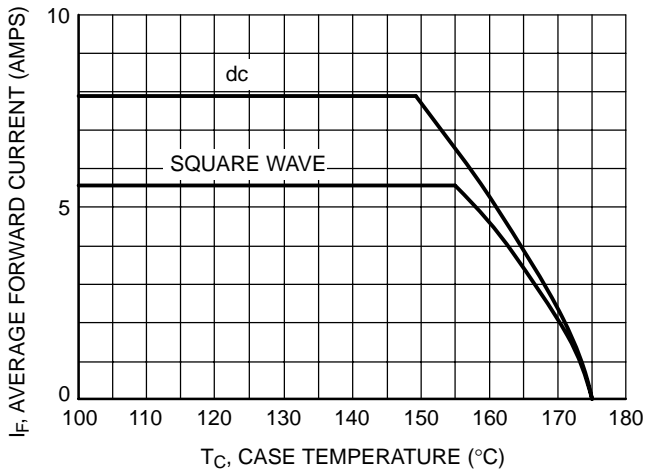


Figure 5. Current Derating

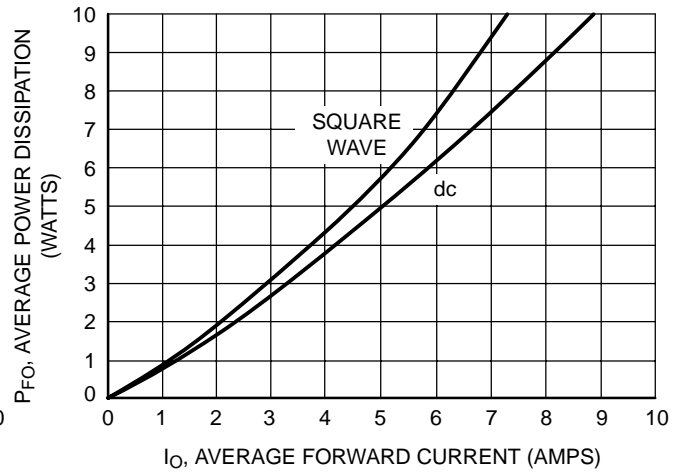


Figure 6. Forward Power Dissipation

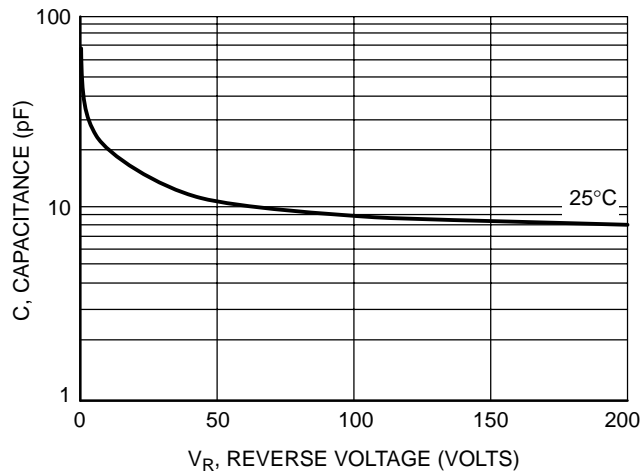


Figure 7. Capacitance

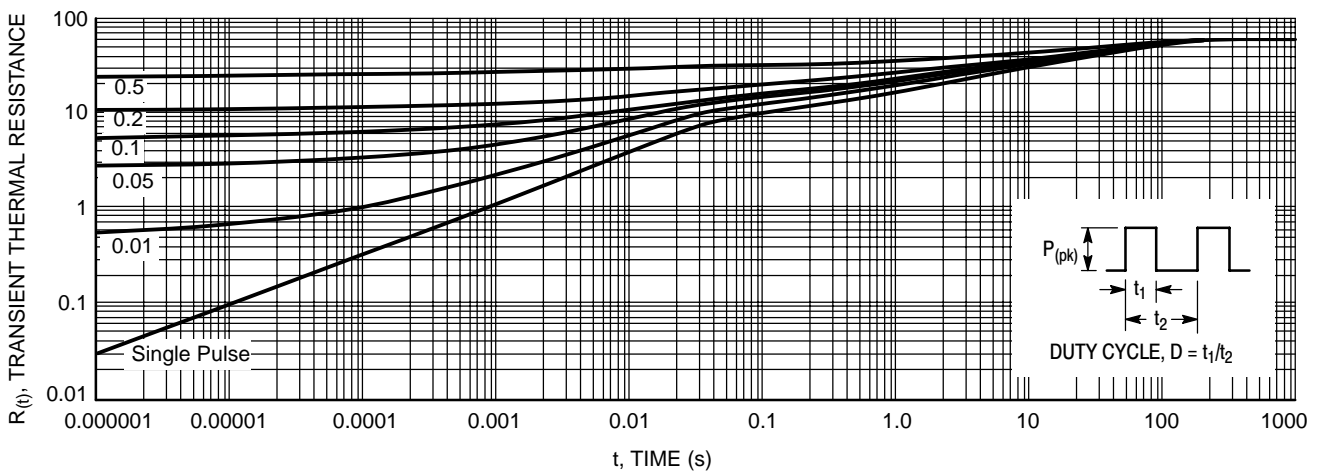


Figure 8. Thermal Response for MUR550APF

MUR550APF, MURD550PF, MUR550PF

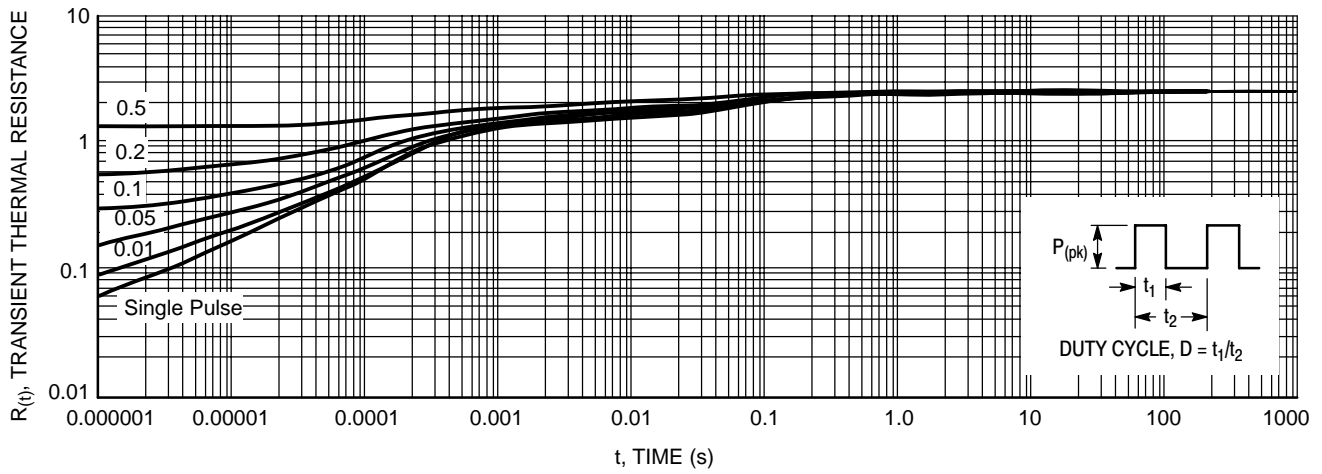


Figure 9. Thermal Response for MURD550PF

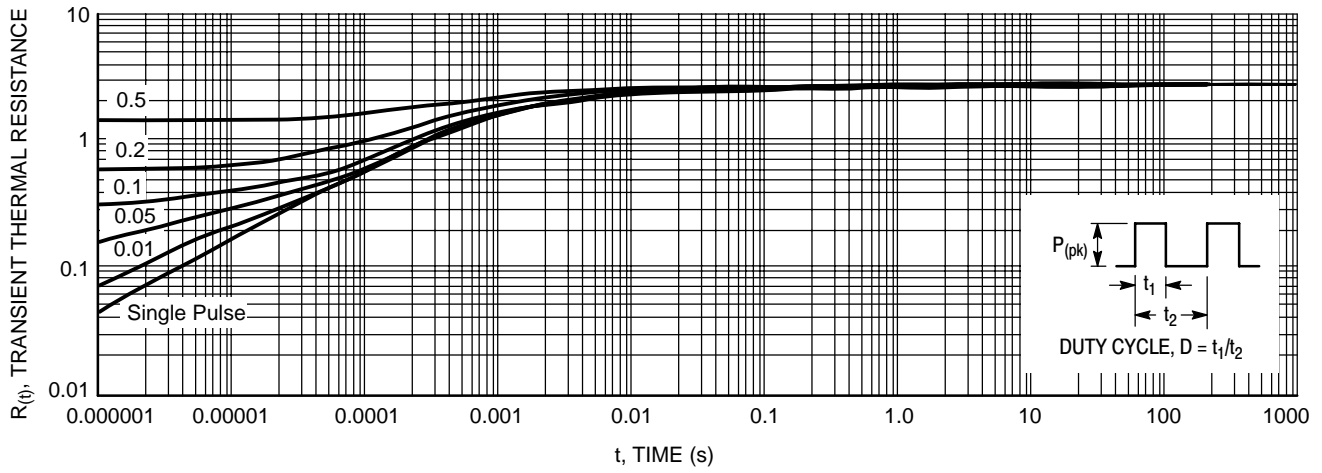


Figure 10. Thermal Response for MUR550PF

## MUR550APF, MURD550PF, MUR550PF

### ORDERING INFORMATION

Device	Package	Shipping†
MUR550APF*	Axial	500 Units/Bag
MUR550APFRL*	Axial	1500 Tape & Reel
MURD550PFT4	DPAK	2500 Tape & Reel
MURD550PFT4G	DPAK (Pb-Free)	2500 Tape & Reel
MUR550PF	TO-220	50 Units/Rail

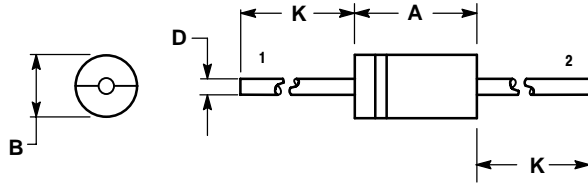
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

\*These devices are manufactured with a Pb-Free external lead finish only.

# MUR550APF, MURD550PF, MUR550PF

## PACKAGE DIMENSIONS

### AXIAL LEAD CASE 267-05 ISSUE G

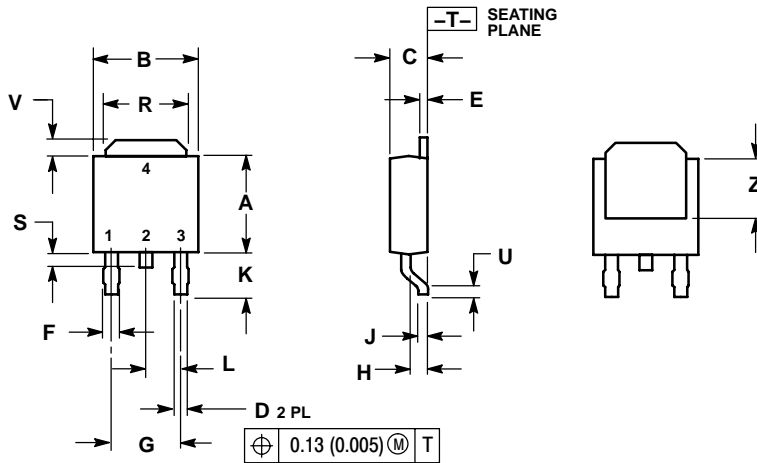


- NOTES:  
 1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.  
 2. CONTROLLING DIMENSION: INCH.  
 3. 267-04 OBSOLETE, NEW STANDARD 267-05.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.287	0.374	7.30	9.50
B	0.189	0.209	4.80	5.30
D	0.047	0.051	1.20	1.30
K	1.000	---	25.40	---

STYLE 1:  
 PIN 1. CATHODE (POLARITY BAND)  
 2. ANODE

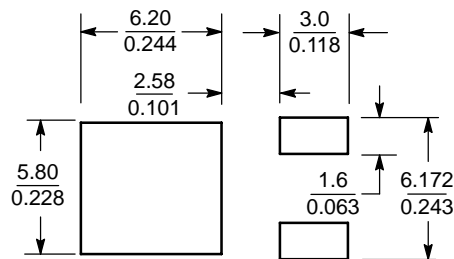
### DPAK CASE 369C-01 ISSUE O



- NOTES:  
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.245	5.97	6.22
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.180 BSC		4.58 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.090 BSC		2.29 BSC	
R	0.180	0.215	4.57	5.45
S	0.025	0.040	0.63	1.01
U	0.020	---	0.51	---
V	0.035	0.050	0.89	1.27
Z	0.155	---	3.93	---

### SOLDERING FOOTPRINT\*



SCALE 3:1 (mm/inches)

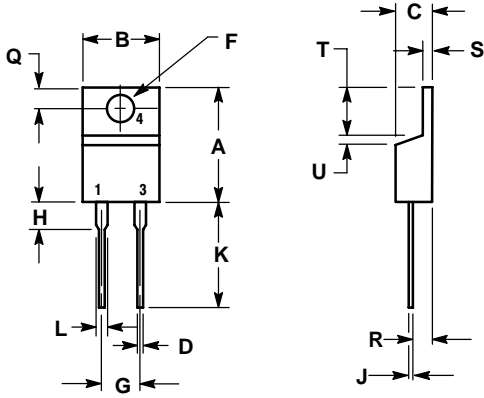
\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



# MUR550APF, MURD550PF, MUR550PF

## PACKAGE DIMENSIONS

TO-220  
CASE 221B-04  
ISSUE D




- NOTES:  
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.595	0.620	15.11	15.75
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.82
D	0.025	0.035	0.64	0.89
F	0.142	0.147	3.61	3.73
G	0.190	0.210	4.83	5.33
H	0.110	0.130	2.79	3.30
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.14	1.52
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.14	1.39
T	0.235	0.255	5.97	6.48
U	0.000	0.050	0.000	1.27

# MUR550APF, MURD550PF, MUR550PF

SWITCHMODE is a trademark of Semiconductor Components Industries, LLC (SCILLC).

**ON Semiconductor** and  are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## PUBLICATION ORDERING INFORMATION

### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor  
P.O. Box 61312, Phoenix, Arizona 85082-1312 USA  
**Phone:** 480-829-7710 or 800-344-3860 Toll Free USA/Canada  
**Fax:** 480-829-7709 or 800-344-3867 Toll Free USA/Canada  
**Email:** [orderlit@onsemi.com](mailto:orderlit@onsemi.com)

**N. American Technical Support:** 800-282-9855 Toll Free  
USA/Canada

**Japan:** ON Semiconductor, Japan Customer Focus Center  
2-9-1 Kamimeguro, Meguro-ku, Tokyo, Japan 153-0051  
**Phone:** 81-3-5773-3850

**ON Semiconductor Website:** <http://onsemi.com>

**Order Literature:** <http://www.onsemi.com/litorder>

For additional information, please contact your  
local Sales Representative.